

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Hiroshi UCHIDA</td><td>05/15/2008</td></tr><tr><td>Tomokazu UMEZAWA</td><td>05/15/2008</td></tr></tbody></table>		Name	Execution Date	Hiroshi UCHIDA	05/15/2008	Tomokazu UMEZAWA	05/15/2008				
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Tomokazu UMEZAWA	05/15/2008										
RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>SHOWA DENKO K.K.</td></tr><tr><td>Street Address:</td><td>13-9, Shibadaimon 1-chome</td></tr><tr><td>City:</td><td>Minato-ku, Tokyo</td></tr><tr><td>State/Country:</td><td>JAPAN</td></tr><tr><td>Postal Code:</td><td>1058518</td></tr></table>		Name:	SHOWA DENKO K.K.	Street Address:	13-9, Shibadaimon 1-chome	City:	Minato-ku, Tokyo	State/Country:	JAPAN	Postal Code:	1058518
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PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12281274</td></tr></tbody></table>		Property Type	Number	Application Number:	12281274						
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Application Number:	12281274										
CORRESPONDENCE DATA											
Fax Number: (202)293-7860 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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NAME OF SUBMITTER:	Bruce E. Kramer										
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PATENT

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REEL: 021464 FRAME: 0506

Assignment of Application

INSERT NAMES
AND RESIDENCE
ADDRESS OF
THE INVENTORS:

WHEREAS, I (WE) 1) Hiroshi UCHIDA and 2) Tomokazu UMEZAWA of c/o SHOWA DENKO K.K., 5-1, Ogimachi, Kawasaki-ku, Kawasaki-shi, Kanagawa 2100867 Japan, respectively,

INSERT TITLE OF
INVENTION:

have invented certain new and useful improvements in: "THERMOSETTING RESIN COMPOSITION AND USES THEREOF"

(Application No. 12/281,274 , filed August 29, 2008), and

INSERT NAMES
AND ADDRESS OF
COMPANY OR
OTHER ASSIGNEE

WHEREAS, SHOWA DENKO K.K.

(hereinafter referred to as "ASSIGNEE") having a place of business at : 13-9, Shibadaimon 1-chome, Minato-ku, Tokyo 1058518 Japan is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I(WE), by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letter Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of Sughrue, Mion, PLLC of 2100 Pennsylvania Avenue, N.W.

Washington, DC 20037-3213

U.S.A the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: May 15, 2008

Hiroshi Uchida
(Signature of Inventor) Hiroshi UCHIDA

Date: May 15, 2008

Tomokazu Umezawa
(Signature of Inventor) Tomokazu UMEZAWA